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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	56800E
Core Size	16-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	26
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc56f8023vlc

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Part 1 Overview

1.1 56F8033/56F8023 Features

1.1.1 Digital Signal Controller Core

- Efficient 16-bit 56800E family Digital Signal Controller (DSC) engine with dual Harvard architecture
- As many as 32 Million Instructions Per Second (MIPS) at 32MHz core frequency
- Single-cycle 16×16 -bit parallel Multiplier-Accumulator (MAC)
- Four 36-bit accumulators, including extension bits
- 32-bit arithmetic and logic multi-bit shifter
- Parallel instruction set with unique DSP addressing modes
- Hardware DO and REP loops
- Three internal address buses
- Four internal data buses
- Instruction set supports both DSP and controller functions
- Controller-style addressing modes and instructions for compact code
- Efficient C compiler and local variable support
- Software subroutine and interrupt stack with depth limited only by memory
- JTAG/Enhanced On-Chip Emulation (OnCE) for unobtrusive, processor speed-independent, real-time debugging

1.1.2 Difference Between Devices

Table 1-1 outlines the key differences between the 56F8033 and 56F8023 devices.

Table 1-1 Device Differences

On-Chip Memory	56F8033	56F8023
Program Flash (PFLASH)	64KB	32KB
Unified RAM (RAM)	8KB	4KB

1.1.3 Memory

- Dual Harvard architecture permits as many as three simultaneous accesses to program and data memory
- Flash security and protection that prevent unauthorized users from gaining access to the internal Flash
- On-chip memory
 - 64KB of Program Flash (56F80233 device)
 32KB of Program Flash (56F8023 device)
 - 8KB of Unified Data/Program RAM (56F8033 device)
 4KB of Unified Data/Program RAM (56F8023 device)
- EEPROM emulation capability using Flash



In Table 2-2, peripheral pins in bold identify reset state.

			Periph	erals:									
Pin #	Pin Name	Signal Name	GPIO	I2C	QSCI	QSPI	ADC	PWM	Quad Timer	Comp	Power & Ground	JTAG	Misc.
1	GPIOB6	GPIOB6, RXD0, SDA, CLKIN	B6	SDA	RXD0								CLKIN
2	GPIOB1	GPIOB1, SSO, SDA	B1	SDA		SS0							
3	GPIOB7	GPIOB7, TXD0, SCL	B7	SCL	TXD0								
4	GPIOB5	GPIOB5, TA1, FAULT3, CLKIN	B5					FAULT3	TA1				CLKIN
5	GPIOC4	GPIOC4, ANB0 & CMPBI3	C4				ANB0			CMPBI3			
6	GPIOC5	GPIOC5, ANB1	C5				ANB1						
7	GPIOC6	GPIOC6, ANB2, V _{REFHB}	C6				ANB2 V _{REFHB}						
8	VDDA	V _{DDA}									V _{DDA}		
9	VSSA	V _{SSA}									V _{SSA}		
10	GPIOC2	GPIOC2, ANA2, V _{REFHA}	C2				ANA2 V _{REFHA}						
11	GPIOC1	GPIOC1, ANA1	C1				ANA1						
12	GPIOC0	GPIOC0, ANA0 & CMPAI3	C0				ANA0			CMPAI3			
13	VSS	V _{SS}									V _{SS}		
14	тск	TCK, GPIOD2	D2									тск	
15	RESET	RESET, GPIOA7	A7										RESET
16	GPIOB3	GPIOB3, MOSI0, TA3, PSRC1	В3			MOSI0		PSRC1	TA3				
17	GPIOB2	GPIOB2, MISO0, TA2, PSRC0	B2			MISO0		PSRC0	TA2				
18	GPIOA6	GPIOA6, FAULT0, TA0	A6					FAULT0	TA0				
19	GPIOB4	GPIOB4, TA0, CLKO, PSRC2	B4					PSRC2	TA0				CLKO
20	GPIOA5	GPIOA5, PWM5, TA3, FAULT2	A5					PWM5 FAULT2	TA3				
21	GPIOB0	GPIOB0, SCLK0, SCL	В0	SCL		SCLK0							
22	GPIOA4	GPIOA4, PWM4, TA2, FAULT1	A4					PWM4 FAULT1	TA2				
23	GPIOA2	GPIOA2, PWM2	A2					PWM2					
24	GPIOA3	GPIOA3, PWM3	A3					PWM3					
25	VCAP	V _{CAP}									V _{CAP}		
26	VDD	V _{DD}									V _{DD}		
27	VSS	V _{SS}									V _{SS}		
28	GPIOA1	GPIOA1, PWM1	A1					PWM1					

Table 2-2 56F8033/56F8023 Pins



Table 2-3 56F8033/56F8023 Signal and Package Information for the 32-Pin LQFP

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description
GPIOA1	28	Input/ Output	Input, internal pull-up	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM1)		Output	enabled	PWM1 — This is one of the six PWM output pins.
				After reset, the default state is GPIOA1.
GPIOA2	23	Input/ Output	Input, internal pull-up	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM2)		Output	enabled	PWM2 — This is one of the six PWM output pins.
				After reset, the default state is GPIOA2.
GPIOA3	24	Input/ Output	Input, internal pull-up	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM3)		Output	enabled	PWM3 — This is one of the six PWM output pins.
				After reset, the default state is GPIOA3.
GPIOA4	22	Input/ Output	Input, internal pull-up	Port A GPIO — This GPIO pin can be individually programmed as an input or output pin.
(PWM4)		Output	enabled	PWM4 — This is one of the six PWM output pins.
(TA2 ¹)		Input/ Output		TA2 — Timer A, Channel 2
(FAULT1 ²)		Input		Fault1 — This fault input pin is used for disabling selected PWM outputs in cases where fault conditions originate off-chip.
				After reset, the default state is GPIOA4. The peripheral functionality is controlled via the SIM. See Section 6.3.16 .
¹ The TA2 signa ² The Fault1 sig	al is also bi Inal is also	ought out on th brought out on	ne GPIOB2-3 pin the GPIOB4 pin	

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Table 2-3 56F8033/56F8023 Signal and Package Information for the 32-Pin LQFP

Signal Name	LQFP Pin No.	Туре	State During Reset	Signal Description			
GPIOB0	21	Input/ Output	Input, internal pull-up	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.			
(SCLK0)		Input/ Output	enableu	QSPI0 Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. A Schmitt trigger input is used for noise immunity.			
(SCL ⁶)		Input/ Output		Serial Clock — This pin serves as the I ² C serial clock. After reset, the default state is GPIOB0. The peripheral functionality is controlled via the SIM. See Section 6.3.16 .			
⁶ The SCL signa	al is also b	rought out on th	ne GPIOB7 pin.				
GPIOB1	2	Input/ Output	Input, internal pull-up enabled	Port B GPIO — This GPIO pin can be individually programmed as an input or output pin.			
(<mark>SS0</mark>)		Input/ Output	chabled	QSPI0 Slave Select — \overline{SS} is used in slave mode to indicate to the QSPI0 module that the current transfer is to be received.			
(SDA ⁷)		Input		Serial Data — This pin serves as the I^2C serial data line.			
				After reset, the default state is GPIOB1. The peripheral functionality is controlled via the SIM. See Section 6.3.16 .			
⁷ The SDA sign	The SDA signal is also brought out on the GPIOB6 pin.						

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Table 4-12 Interrupt Control Registers Address Map (Continued) (ITCN_BASE = \$00 F0E0)

Register Acronym	Address Offset	Register Description
ITCN_FIM0	\$8	Fast Interrupt Match 0 Register
ITCN_FIVAL0	\$9	Fast Interrupt Vector Address Low 0 Register
ITCN_FIVAH0	\$A	Fast Interrupt Vector Address High 0 Register
ITCN_FIM1	\$B	Fast Interrupt Match 1 Register
ITCN_FIVAL1	\$C	Fast Interrupt Vector Address Low 1 Register
ITCN_FIVAH1	\$D	Fast Interrupt Vector Address High 1 Register
ITCN_IRQP0	\$E	IRQ Pending Register 0
ITCN_IRQP1	\$F	IRQ Pending Register 1
ITCN_IRQP2	\$10	IRQ Pending Register 2
ITCN_IRQP3	\$11	IRQ Pending Register 3
		Reserved
ITCN_ICTRL	\$16	Interrupt Control Register
		Reserved

Table 4-13 SIM Registers Address Map (SIM_BASE = \$00 F100)

Register Acronym	Address Offset	Register Description
SIM_CTRL	\$0	Control Register
SIM_RSTAT	\$1	Reset Status Register
SIM_SWC0	\$2	Software Control Register 0
SIM_SWC1	\$3	Software Control Register 1
SIM_SWC2	\$4	Software Control Register 2
SIM_SWC3	\$5	Software Control Register 3
SIM_MSHID	\$6	Most Significant Half JTAG ID
SIM_LSHID	\$7	Least Significant Half JTAG ID
SIM_PWR	\$8	Power Control Register
		Reserved
SIM_CLKOUT	\$A	Clock Out Select Register
SIM_PCR	\$B	Peripheral Clock Rate Register
SIM_PCE0	\$C	Peripheral Clock Enable Register 0
SIM_PCE1	\$D	Peripheral Clock Enable Register 1
SIM_SD0	\$E	Peripheral STOP Disable Register 0
SIM_SD1	\$F	Peripheral STOP Disable Register 1
SIM_IOSAHI	\$10	I/O Short Address Location High Register
SIM_IOSALO	\$11	I/O Short Address Location Low Register
SIM_PROT	\$12	Protection Register
SIM_GPSA0	\$13	GPIO Peripheral Select Register 0 for GPIOA

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Table 4-23 Digital-to-Analog Converter 0 Registers Address Map
(DAC0_BASE = \$00 F1C0)

Register Acronym	Address Offset	Register Description
DAC0_CTRL	\$0	Control Register
DAC0_DATA	\$1	Data Register
DAC0_STEP	\$2	Step Register
DAC0_MINVAL	\$3	Minimum Value Register
DAC0_MAXVAL	\$4	Maximum Value Register

Table 4-24 Comparator A Registers Address Map (CMPA_BASE = \$00 F1E0)

Register Acronym	Address Offset	Register Description
CMPA_CTRL	\$0	Control Register
CMPA_STAT	\$1	Status Register
CMPA_FILT	\$2	Filter Register

Table 4-25 Comparator B Registers Address Map (CMPB_BASE = \$00 F1F0)

Register Acronym	Address Offset	Register Description
CMPB_CTRL	\$0	Control Register
CMPB_STAT	\$1	Status Register
CMPB_FILT	\$2	Filter Register

Table 4-26 Queued Serial Communication Interface 0 Registers Address Map (QSCI0_BASE = \$00 F200)

Register Acronym	Address Offset	Register Description
QSCI0_RATE	\$0	Baud Rate Register
QSCI0_CTRL1	\$1	Control Register 1
QSCI0_CTRL2	\$2	Control Register 2
QSCI0_STAT	\$3	Status Register
QSCI0_DATA	\$4	Data Register



5.4 Block Diagram



Figure 5-1 Interrupt Controller Block Diagram

5.5 Operating Modes

The ITCN module design contains two major modes of operation:

• Functional Mode

The ITCN is in this mode by default.

• Wait and Stop Modes

During Wait and Stop modes, the system clocks and the 56800E core are turned off. The ITCN will signal a pending IRQ to the System Integration Module (SIM) to restart the clocks and service the IRQ. An IRQ can only wake up the core if the IRQ is enabled prior to entering the Wait or Stop mode.

5.6 Register Descriptions

A register address is the sum of a base address and an address offset. The base address is defined at the



5.6.11.2 Fast Interrupt 0 Vector Address High (FIVAH0)—Bits 4–0

The upper five bits of the vector address used for Fast Interrupt 0. This register is combined with FIVAL0 to form the 21-bit vector address for Fast Interrupt 0 defined in the FIM0 register.

5.6.12 Fast Interrupt 1 Match Register (FIM1)

Base + \$B	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	FAST INTERRUPT 1					
Write											FAST INTERROPT I					
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-14 Fast Interrupt 1 Match Register (FIM1)

5.6.12.1 Reserved—Bits 15-6

This bit field is reserved. Each bit must be set to 0.

5.6.12.2 Fast Interrupt 1 Vector Number (FAST INTERRUPT 1)—Bits 5–0

These values determine which IRQ will be Fast Interrupt 1. Fast Interrupts vector directly to a service routine based on values in the Fast Interrupt Vector Address registers without having to go to a jump table first. IRQs used as Fast Interrupts *must* be set to priority level 2. Unexpected results will occur if a Fast Interrupt vector is set to any other priority. A Fast Interrupt automatically becomes the highest priority level 2 interrupt, regardless of its location in the interrupt table prior to being declared as Fast Interrupt. Fast Interrupt 0 has priority over Fast Interrupt 1. To determine the vector number of each IRQ, refer to the vector table.

5.6.13 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

Base + \$C	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read						FAST IN	ITERRI		CTOR		SS LOW					
Write		FAST INTERROFT I VECTOR ADDRESS LOW														
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-15 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

5.6.13.1 Fast Interrupt 1 Vector Address Low (FIVAL1)—Bits 15–0

The lower 16 bits of the vector address used for Fast Interrupt 1. This register is combined with FIVAH1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.14 Fast Interrupt 1 Vector Address High (FIVAH1)

Base + \$D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	FAST INTERRUPT 1 VECTOR				OR
Write													ADDRESS HIGH			
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-16 Fast Interrupt 1 Vector Address High Register (FIVAH1)



6.3.11.2 Comparator A Clock Stop Disable (CMPA_SD)—Bit 14

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.3 Digital-to-Analog Converter 0 Clock Stop Disable (DAC1_SD)—Bit 13

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.4 Digital-to-Analog Converter 0 Clock Stop Disable (DAC0_SD)—Bit 12

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.5 Reserved—Bit 11

This bit field is reserved. It must be set to 0.

6.3.11.6 Analog-to-Digital Converter Clock Stop Disable (ADC_SD)—Bit 10

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.7 Reserved—Bits 9–7

This bit field is reserved. Each bit must be set to 0.

6.3.11.8 Inter-Integrated Circuit Clock Stop Disable (I2C_SD)—Bit 6

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.9 Reserved—Bit 5

This bit field is reserved. It must be set to 0.

6.3.11.10 QSCI0 Clock Stop Disable (QSCI0_SD)—Bit 4

- 0 = The clock is disabled during Stop mode
- 1 = The clock is enabled during Stop mode if the clock to this peripheral is enabled in the SIM_PCE0 register

6.3.11.11 Reserved—Bit 3

This bit field is reserved. It must be set to 0.



6.3.17.3 Configure GPIOB5 (GPS_B5)—Bits 12–11

This field selects the alternate function for GPIOB5.

- 00 = TA1 Timer A1 (default)
- 01 = FAULT3 PWM FAULT3 Input
- 10 = CLKIN External Clock Input
- 11 = Reserved

6.3.17.4 Configure GPIOB4 (GPS_B4)—Bits 10-8

This field selects the alternate function for GPIOB4.

- 000 = TA0 Timer A0 (default)
- 001 = CLKO Clock Output
- 010 = Reserved
- 011 = TB0 Timer B0
- 100 = PSRC2 PWM4 / PWM5 Pair External Source
- 11x = Reserved
- 1x1 = Reserved

6.3.17.5 Configure GPIOB3 (GPS_B3)—Bits 7–6

This field selects the alternate function for GPIOB3.

- 00 = MOSI0 QSPI0 Master Out/Slave In (default)
- 01 = TA3 Timer A3
- 10 = PSRC1 PWM2 / PWM3 Pair External Source
- 11 = Reserved

6.3.17.6 Configure GPIOB2 (GPS_B2)—Bits 5–4

This field selects the alternate function for GPIOB2.

- 00 = MISO0 QSPI0 Master In/Slave Out (default)
- 01 = TA2 Timer A2
- 10 = PSRC0 PWM0 / PWM1 Pair External Source
- 11 = Reserved

6.3.17.7 Reserved—Bit 3

This bit field is reserved. It must be set to 0.

6.3.17.8 Configure GPIOB1 (GPS_B1)—Bit 2

This field selects the alternate function for GPIOB1.

- $0 = \overline{SS0}$ QSPI0 Slave Select (default)
- 1 = SDA I2C Serial Data



Add. Offset	Register Acronym		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	GPIOD_PUPEN	R W RS	0	0	0	0	0	0	0	0	1	1	1	1	1	PU[1 1	15:0] 1	1
\$1	GPIOD_DATA	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	D[1 0	5:0] 0	0
\$2	GPIOD_DDIR	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	DD[1 0	15:0] 0	0
\$3	GPIOD_PEREN	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	1	PE[1 1	15:0] 1	1
\$4	GPIOD_IASSRT	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	IA[1 0	5:0] 0	0
\$5	GPIOD_IEN	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	IEN[⁻ 0	15:0] 0	0
\$6	GPIOD_IEPOL	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	IEPOL 0	_[15:0] 0	0
\$7	GPIOD_IPEND	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	IPR[[*] 0	15:0] 0	0
\$8	GPIOD_IEDGE	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	IES[[^]	15:0] 0	0
\$9	GPIOD_PPOUTM	R W RS	0	0	0	0	0	0	0	0	1	1	1	1	1	OEN[1	[15:0] 1	1
\$A	GPIOD_RDATA	R W RS	0	0	0	0	0	0	0	0	X	X	Х	X	RA X	W DA	TA[15 X	:0] X
\$В	GPIOD_DRIVE	R W RS	0	0	0	0	0	0	0	0	0	0	0	0	0	DRIVE 0	[15:0] 0	0
		R W RS	0	Read Rese Reset	l as 0 rved													

Figure 8-4 GPIOD Register Map Summary

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Part 9 Joint Test Action Group (JTAG)

9.1 56F8033/56F8023 Information

Please contact your Freescale sales representative or authorized distributor for device/package-specific BSDL information.

The $\overline{\text{TRST}}$ pin is not available in this package. The pin is tied to V_{DD} in the package.

The JTAG state machine is reset during POR and can also be reset via a soft reset by holding TMS high for five rising edges of TCK, as described in the **56F802X and 56F803X Peripheral Reference Manual**.

Part 10 Specifications

10.1 General Characteristics

The 56F8033/56F8023 is fabricated in high-density CMOS with 5V-tolerant TTL-compatible digital inputs. The term "5V-tolerant" refers to the capability of an I/O pin, built on a 3.3V-compatible process technology, to withstand a voltage up to 5.5V without damaging the device. Many systems have a mixture of devices designed for 3.3V and 5V power supplies. In such systems, a bus may carry both 3.3V- and 5V-compatible I/O voltage levels (a standard 3.3V I/O is designed to receive a maximum voltage of 3.3V \pm 10% during normal operation without causing damage). This 5V-tolerant capability therefore offers the power savings of 3.3V I/O levels, combined with the ability to receive 5V levels without damage.

Absolute maximum ratings in **Table 10-1** are stress ratings only, and functional operation at the maximum is not guaranteed. Stress beyond these ratings may affect device reliability or cause permanent damage to the device.

Unless otherwise stated, all specifications within this chapter apply over the temperature range of -40°C to 125°C ambient temperature over the following supply ranges:

 V_{SS} = V_{SSA} = 0V, V_{DD} = V_{DDA} = 3.0–3.6V, CL \leq 50pF, f_{OP} = 32MHz

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Characteristic	Symbol	Notes	Min	Мах	Unit
Supply Voltage Range	V _{DD}		-0.3	4.0	V
Analog Supply Voltage Range	V _{DDA}		- 0.3	4.0	V
ADC High Voltage Reference	V _{REFHx}		- 0.3	4.0	V
Voltage difference V _{DD} to V _{DDA}	ΔV_{DD}		- 0.3	0.3	V
Voltage difference V_{SS} to V_{SSA}	ΔV_{SS}		- 0.3	0.3	V
Digital Input Voltage Range	V _{IN}	Pin Groups 1, 2	- 0.3	6.0	V
Oscillator Voltage Range	V _{OSC}	Pin Group 4	- 0.4	4.0	V
Analog Input Voltage Range	V _{INA}	Pin Group 3	- 0.3	4.0	V
Input clamp current, per pin (V _{IN} < 0) ¹	V _{IC}		_	-20.0	mA
Output clamp current, per pin (V _O < 0) ¹	V _{OC}		_	-20.0	mA
Output Voltage Range (Normal Push-Pull mode)	V _{OUT}	Pin Group 1	- 0.3	4.0	V
Output Voltage Range (Open Drain mode)	V _{OUTOD}	Pin Group 2	- 0.3	6.0	V
Ambient Temperature Industrial	T _A		- 40	105	°C
Storage Temperature Range (Extended Industrial)	T _{STG}		- 55	150	°C

Table 10-1 Absolute Maximum Ratings $(V_{SS} = 0V, V_{SSA} = 0V)$

1. Continuous clamp current per pin is -2.0 mA

Default Mode

Pin Group 1: GPIO, TDI, TDO, TMS, TCK Pin Group 2: RESET, GPIOA7 Pin Group 3: ADC and Comparator Analog Inputs Pin Group 4: XTAL, EXTAL

10.1.1 ElectroStatic Discharge (ESD) Model

Table 10-2 56F8033/56F8023 ESD Protection

Characteristic	Min	Тур	Мах	Unit
ESD for Human Body Model (HBM)	2000	_	_	V



measured directly on the V_{CAP} pin. The specifications for this regulator are shown in Table 10-8.

Characteristic	Symbol	Min	Typical	Мах	Unit
Short Circuit Current	I _{SS}		450	650	mA
Short Circuit Tolerance (V _{CAP} shorted to ground)	T _{RSC}	—	—	30	minutes

Table 10-8. Regulator Parameters

10.3 AC Electrical Characteristics

Tests are conducted using the input levels specified in **Table 10-5**. Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured between the 10% and 90% points, as shown in **Figure 10-2**.



Note: The midpoint is V_{IL} + $(V_{IH} - V_{IL})/2$.

Figure 10-2 Input Signal Measurement References

Figure 10-3 shows the definitions of the following signal states:

- Active state, when a bus or signal is driven, and enters a low impedance state
- Tri-stated, when a bus or signal is placed in a high impedance state
- Data Valid state, when a signal level has reached V_{OL} or V_{OH}
- Data Invalid state, when a signal level is in transition between V_{OL} and V_{OH}



Figure 10-3 Signal States







Figure 10-14 Timing Definition for Fast and Standard Mode Devices on the I²C Bus

10.13 JTAG Timing

Characteristic	Symbol	Min	Мах	Unit	See Figure
TCK frequency of operation ¹	f _{OP}	DC	SYS_CLK/8	MHz	10-15
TCK clock pulse width	t _{PW}	50	—	ns	10-15
TMS, TDI data set-up time	t _{DS}	5	—	ns	10-16
TMS, TDI data hold time	t _{DH}	5	—	ns	10-16
TCK low to TDO data valid	t _{DV}	_	30	ns	10-16
TCK low to TDO tri-state	t _{TS}	—	30	ns	10-16

Table 10-18 JTAG Timing

1. TCK frequency of operation must be less than 1/8 the processor rate.



Figure 10-15 Test Clock Input Timing Diagram

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10.14 Analog-to-Digital Converter (ADC) Parameters

Parameter	Symbol	Min	Тур	Max	Unit
DC Specifications				•	
Resolution	R _{ES}	12	—	12	Bits
ADC internal clock	f _{ADIC}	0.1	_	5.33	MHz
Conversion range	R _{AD}	V _{REFL}	_	V _{REFH}	V
ADC power-up time ²	t _{ADPU}	—	6	13	t _{AIC} cycles ³
Recovery from auto standby	t _{REC}	—	0	1	t _{AIC} cycles ³
Conversion time	t _{ADC}	—	6	—	t _{AIC} cycles ³
Sample time	t _{ADS}	—	1	—	t _{AIC} cycles ³
Accuracy					•
Integral non-linearity ⁴ (Full input signal range)	INL	_	+/- 3	+/- 5	LSB ⁵
Differential non-linearity	DNL	—	+/6	+/- 1	LSB ⁵
Monotonicity			GUARANTEED		
Offset Voltage Internal Ref	V _{OFFSET}	—	+/- 4	+/- 9	mV
Offset Voltage External Ref	V _{OFFSET}	—	+/- 6	+/- 12	mV
Gain Error (transfer gain)	E _{GAIN}	—	.998 to 1.002	1.01 to .99	_
ADC Inputs ⁶ (Pin Group 3)					
Input voltage (external reference)	V _{ADIN}	V _{REFL}	_	V _{REFH}	V
Input voltage (internal reference)	V _{ADIN}	V _{SSA}	—	V _{DDA}	V
Input leakage	Ι _{ΙΑ}	—	0	+/- 2	μΑ
V _{REFH} current	I _{VREFH}	—	0	—	μΑ
Input injection current ⁷ , per pin	I _{ADI}	—	_	3	mA
Input capacitance	C _{ADI}	—	See Figure 10-17	—	pF
Input impedance	X _{IN}	—	See Figure 10-17	—	Ohms
AC Specifications					•
Signal-to-noise ratio	SNR	60	65		dB
Total Harmonic Distortion	THD	60	64		dB
Spurious Free Dynamic Range	SFDR	61	66		dB
Signal-to-noise plus distortion	SINAD	58	62		dB
Effective Number Of Bits	ENOB	—	10.0		Bits

Table 10-19 ADC Parameters¹

1. All measurements were made at V_{DD} = 3.3V, V_{REFH} = 3.3V, and V_{REFL} = ground

2. Includes power-up of ADC and V_{REF}

3. ADC clock cycles

4. INL measured from V_{IN} = V_{REFL} to V_{IN} = V_{REFH}

5. LSB = Least Significant Bit = 0.806mV

6. Pin groups are detailed following Table 10-1.



• Cload is expressed in pF

Because of the low duty cycle on most device pins, power dissipation due to capacitive loads was found to be fairly low when averaged over a period of time.

E, the external [static component], reflects the effects of placing resistive loads on the outputs of the device. Sum the total of all V²/R or IV to arrive at the resistive load contribution to power. Assume V = 0.5 for the purposes of these rough calculations. For instance, if there is a total of eight PWM outputs driving 10mA into LEDs, then P = 8*.5*.01 = 40mW.

In previous discussions, power consumption due to parasitics associated with pure input pins is ignored, as it is assumed to be negligible.



Part 11 Packaging

11.1 56F8033/56F8023 Package and Pin-Out Information

This section contains package and pin-out information for the 56F8033/56F8023. This device comes in a 32-pin Low-profile Quad Flat Pack (LQFP). Figure 11-1 shows the package outline, Figure 11-2 shows the mechanical parameters and Table 11-1 lists the pin-out.



Figure 11-1 Top View, 56F8033/56F8023 32-Pin LQFP Package



The thermal characterization parameter is measured per JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

When heat sink is used, the junction temperature is determined from a thermocouple inserted at the interface between the case of the package and the interface material. A clearance slot or hole is normally required in the heat sink. Minimizing the size of the clearance is important to minimize the change in thermal performance caused by removing part of the thermal interface to the heat sink. Because of the experimental difficulties with this technique, many engineers measure the heat sink temperature and then back-calculate the case temperature using a separate measurement of the thermal resistance of the interface. From this case temperature, the junction temperature is determined from the junction-to-case thermal resistance.

12.2 Electrical Design Considerations

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Use the following list of considerations to assure correct operation of the 56F8033/56F8023:

- Provide a low-impedance path from the board power supply to each V_{DD} pin on the 56F8033/56F8023 and from the board ground to each V_{SS} (GND) pin
- The minimum bypass requirement is to place $0.01-0.1\mu$ F capacitors positioned as close as possible to the package supply pins. The recommended bypass configuration is to place one bypass capacitor on each of the V_{DD}/V_{SS} pairs, including V_{DDA}/V_{SSA} . Ceramic and tantalum capacitors tend to provide better tolerances.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{DD} and V_{SS} (GND) pins are as short as possible
- Bypass the V_{DD} and V_{SS} with approximately 100 μ F, plus the number of 0.1 μ F ceramic capacitors
- PCB trace lengths should be minimal for high-frequency signals
- Consider all device loads as well as parasitic capacitance due to PCB traces when calculating capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{DD} and V_{SS} circuits.



Register Name	Peripheral Mar	Reference nual	Data	Sheet	Processor Expert	Memory Address		
	New Acronym	Legacy Acronym	New Acronym	Legacy Acronym Acronym			End	
Timeout Register	TOUT	COPTO	COP_TOUT	COPTO	COPTO	0XF	121	
Counter Register	CNTR	COPCTR	COP_CNTR	COPCTR	COPCTR	0XF	122	

Table 14-1 Legacy and Revised Acronyms (Continued)